## **BAL-NRF02D3**



# 50 ohm nominal input / conjugate match balun to nRF51822-CEAA and nRF51422-CEAA

Datasheet - production data

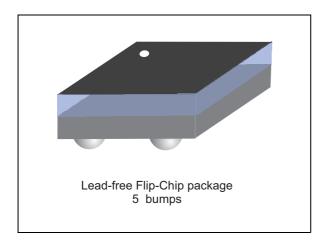
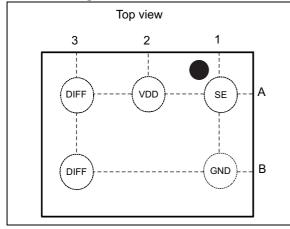


Figure 1. Pin coordinates



#### **Features**

- 50 Ω nominal input / conjugate match to Nordic Semiconductor chips nRF51422-CEAA and nRF51822-CEAA.
- Low insertion loss
- Low amplitude imbalance
- Low phase imbalance
- Small footprint: < 1.2 mm<sup>2</sup>

#### **Benefits**

- Very low profile: < 560 μm after reflow</li>
- High RF performance
- · RF BOM and area reduction

## **Applications**

- 2.45 GHz impedance matched balun filter
- Optimized for Nordic's chip set nRF51422-CEAA, nRF51822-CEAA.

#### **Description**

STMicroelectronics BAL-NRF02D3 is an ultraminiature balun. The BAL-NRF02D3 integrates matching network and harmonics filter. Matching impedance has been customized for the following Nordic Semiconductor circuits: nRF51422-CEAA and nRF51822-CEAA.

The BAL-NRF02D3 uses STMicroelectronics IPD technology on non-conductive glass substrate which optimize RF performances.

The BAL-NRF02D3 has been tested and approved by Nordic Semiconductor in the nRFgo modules.

Application BAL-NRF02D3

# 1 Application

12pF de 16MHz C2 12pF C8 100nF VDCC P0.30 P0.31 P0.00 P0.01 P0.02 P0.01 P0.02 P0.01 P0.02 P0.02 P0.02 P0.04 P0.05 P0.04 P0.05 P VCC\_nRF VCC\_nRF AVDD VSS VSS P0.30 P0.31 P0.00 P0.01 P0.02 P0.03 P0.04 P0.05 P0.06 P0.07 G6 G9 D7 C1 D1 □ E1 F1 C7 VSS ANT2 100nF A1RF ANT2 ANT1 B1 P0.03 P0.04 P0.05 VDD\_PA \_\_\_\_\_\_DEC2 \_\_\_\_\_\_P0.20 \_\_\_\_\_\_P0.19 VDD\_PAGND 0.04 | DEC2 | DEC2 | D.05 | D. P0.20 P0.19 P0.18 P0.17 BAL-NRF02D3 P0.06 P0.07 VDD VCC\_nRF C11\_ C10 47nF =C3 2.2nF 100nF nRF51822-CEAA R1 12k

Figure 2. Application schematic

BAL-NRF02D3 Characteristics

# 2 Characteristics

Table 1. Absolute maximum ratings (limiting values)

Symbol	Parameter	Value			Unit	
	Farameter		Тур.	Max.	Unit	
P <sub>IN</sub>	Input Power RFIN			20	dBm	
V <sub>ESD</sub>	ESD ratings human body model (JESD22-A114-C), all I/O one at a time while others connected to GND	2000				
	ESD ratings charge device model (JESD22-C101-C)	500			V	
	ESD ratings machine model, all I/O	200				
T <sub>OP</sub>	Operating temperature (JESD22-A115-C), all I/O	-40		+85	°C	

## Table 2. Impedances ( $T_{amb} = 25 \, ^{\circ}C$ )

Symbol	Parameter	Value			
Symbol	r ai ailletei	Min.	Тур.	Max.	Unit
Z <sub>OUT</sub>	Z <sub>OUT</sub> Nominal differential output impedance		matched		Ω
Z <sub>IN</sub>	Nominal input impedance		50		Ω

## Table 3. RF performance (T<sub>amb</sub> = 25 °C)

Symbol	Parameter	Test condition	Value			Unit
		rest condition	Min.	Тур.	Max.	Offic
F	Frequency range (bandwidth)		2400		2540	MHz
IL	Insertion loss in bandwidth			1.9		dB
R <sub>L</sub>	Return loss in bandwidth			12		dB
фimb	Phase imbalance			6		0
Aimb	Amplitude imbalance			0.15		dB
2f0	2nd harmonic S21 attenuation	4880 MHz		10		dB
3f0	3rd harmonic S21 attenuation	7320 MHz		20		dB

Characteristics **BAL-NRF02D3** 

#### 2.1 **On-board measurements**

Figure 4. Insertion loss (T<sub>amb</sub> = 25 °C)

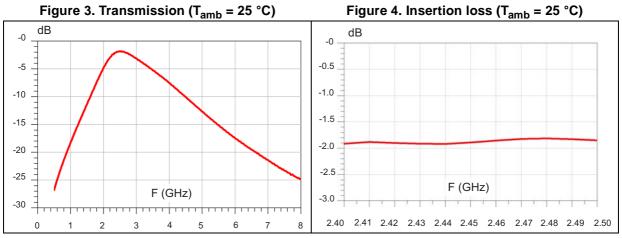


Figure 5. Return loss on SE port  $(T_{amb} = 25 °C)$ 

Figure 6. Return loss on DIFF port  $(T_{amb} = 25 °C)$ 

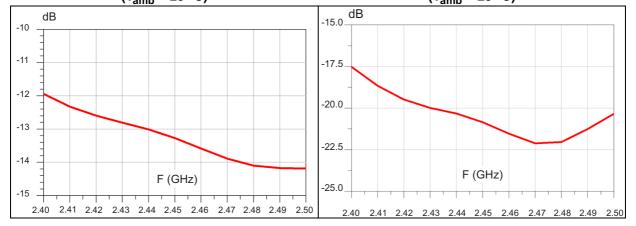
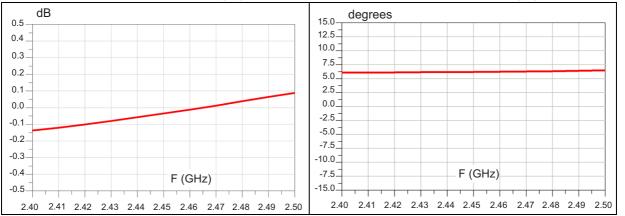


Figure 7. Amplitude imbalance ( $T_{amb} = 25$  °C)

Figure 8. Phase imbalance ( $T_{amb} = 25 \, ^{\circ}C$ )



# 3 Package information

- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <a href="https://www.st.com">www.st.com</a>. ECOPACK<sup>®</sup> is an ST trademark.

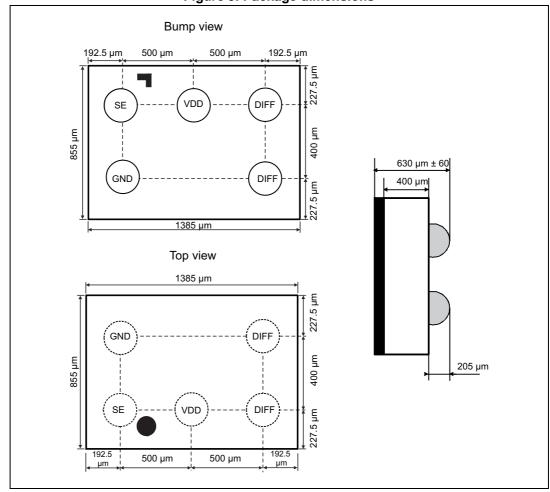


Figure 9. Package dimensions

Package information BAL-NRF02D3

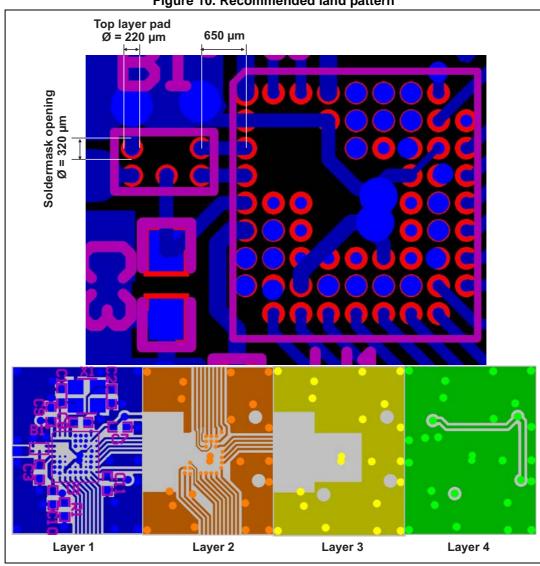
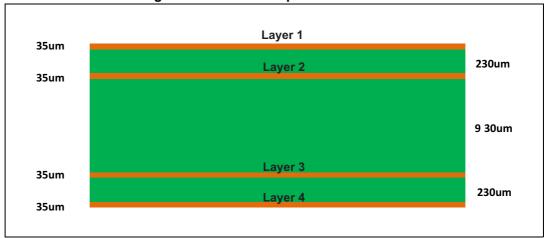


Figure 10. Recommended land pattern





BAL-NRF02D3 Package information

Figure 12. Footprint - non solder mask defined

Figure 13. Footprint - solder mask defined

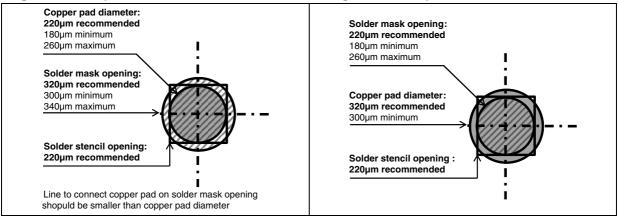
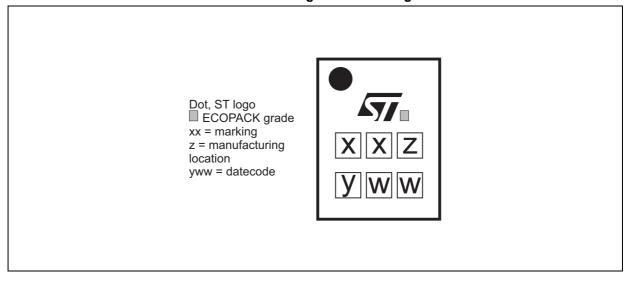


Figure 14. Marking



Package information BAL-NRF02D3

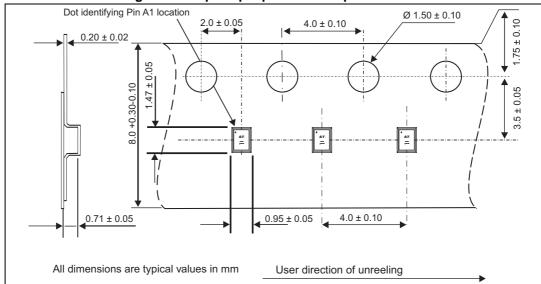


Figure 15. Flip Chip tape and reel specifications

Note:

More information is available in the STMicroelectronics Application notes: AN2348 Flip-Chip: "Package description and recommendations for use" AN4315: "BAL-NRF02D3 matched balun with integrated harmonics filter for Nordic Semiconductor ultralow power transceivers"

# 4 Ordering information

**Table 4. Ordering information** 

Order code	Marking	Weight	Base Qty	Delivery mode
BAL-NRF02D3	SK	1.58 mg	5000	Tape and Reel

# 5 Revision history

**Table 5. Document revision history** 

Date	Revision	Changes
02-Jul-2013	1	Initial release
30-Aug-2013	2	Updated Table 1.

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